

PC93

Non-Silicone Thermal Pad

REACH

RoHS

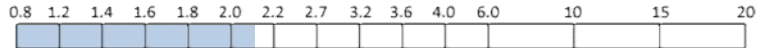
UL



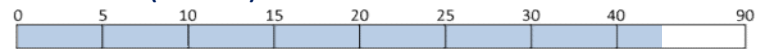
Features

- Non siloxane and oil-bleed
- Ultra soft and great elongation
- Very low thermal impedance
- Electrical insulation
- Great thermal conductivity

Thermal Conductivity: 2.1 W / mK



Hardness: 55 (Shore 00)

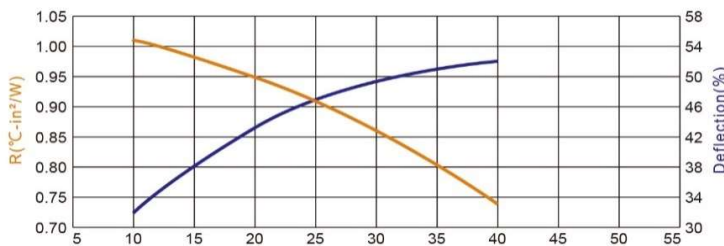


Applications

Applications that require no silicone

Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R (°C-in ² /W)	Deflection (%)
10	1.01	16
20	0.95	32
40	0.74	43

Properties

Properties	PC93	Unit	Tolerance	Test Method
Thermal Conductivity	2.1	W / mK	10%	ASTM D5470
Thickness	0.5~5.0	mm	-	ASTM D374
	0.0197~0.1969	inch	-	ASTM D374
Color	Gray	-	-	Visual
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	10.2	KV / mm	±1	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	2.1	g / cm ³	±0.2	ASTM D792
Working Temperature	-30 ~ +125	°C	-	-
Volume Resistance	>10 ¹⁰	Ohm-m	-	ASTM D257
Elongation	350	%	-	ASTM D412
Tensile Strength	1	Kgf / cm ²	-	ASTM D412
Standard Shape	Sheet ones	-	-	-
Hardness	55	Shore 00	±10	ASTM D2240

Need samples? **Pre-cut for different shapes**

高柏科技 T-Global Techonology Co., Ltd

Provide professional thermal engineering solutions and full range of products.

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version16

20190130

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